

Appl. No. 10/766,491
Reply to Office action of 09/15/2005

REMARKS

Reconsideration of the above-referenced application in view of the above amendment, and of the following remarks, is respectfully requested.

Claims 21-32 are pending in this case. Claims 1-20 are cancelled herein and claims 21-32 are added herein to more completely cover that which Applicant regards as the invention.

The Examiner objected to claims 1, 2, 4-6, and 8-12 due to informalities. Claims 1-14 are cancelled.

The Examiner rejected claims 1-7 and 10-13 under 35 U.S.C. 102(e) as being anticipated by Chikarmane et al. (U.S. 2003/0034251). The Examiner rejected claims 8 and 9 under 35 U.S.C. § 103(a) as being unpatentable over Chikarmane et al. (U.S. 2003/0034251), as applied to claim 1, in view of May et al. (U.S. 2005/0064708). The Examiner rejected claim 14 under 35 U.S.C. § 103(a) as being unpatentable over Chikarmane et al. (U.S. 2003/0034251), in view of Lu et al. (U.S. 2005/0031876).

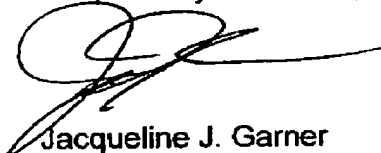
While claims 1-14 are cancelled herein, newly added claims 21-32 are believed to be patentable over the references. Applicant respectfully submits that claim 21 is patentable over the references as there is no disclosure or suggestion in the references of forming a thin layer of oxide over a seed layer within an enclosure, removing the substrate from the enclosure, and placing the substrate with the thin layer of oxide in an electroplating solution. Chikarmane teaches forming an oxide passivation layer over a seed layer. However, Chikarmane teaches removing the passivation layer prior to placing the substrate in the electroplating solution (paragraph [0035] and FIG. 1e showing the passivation layer 18 removed). Chikarmane does not disclose or suggest

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placing the thin layer of oxide in the electroplating solution as required by the claim.
May is added to teach seed layer and barrier layer formation pressures and Lu is added to teach common organic surface contaminants. Accordingly, Applicant respectfully submits that claim 21 and the claims dependent thereon are patentable over the references.

In light of the above, Applicant respectfully requests withdrawal of the Examiner's rejections and allowance of claims 21-32. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,



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